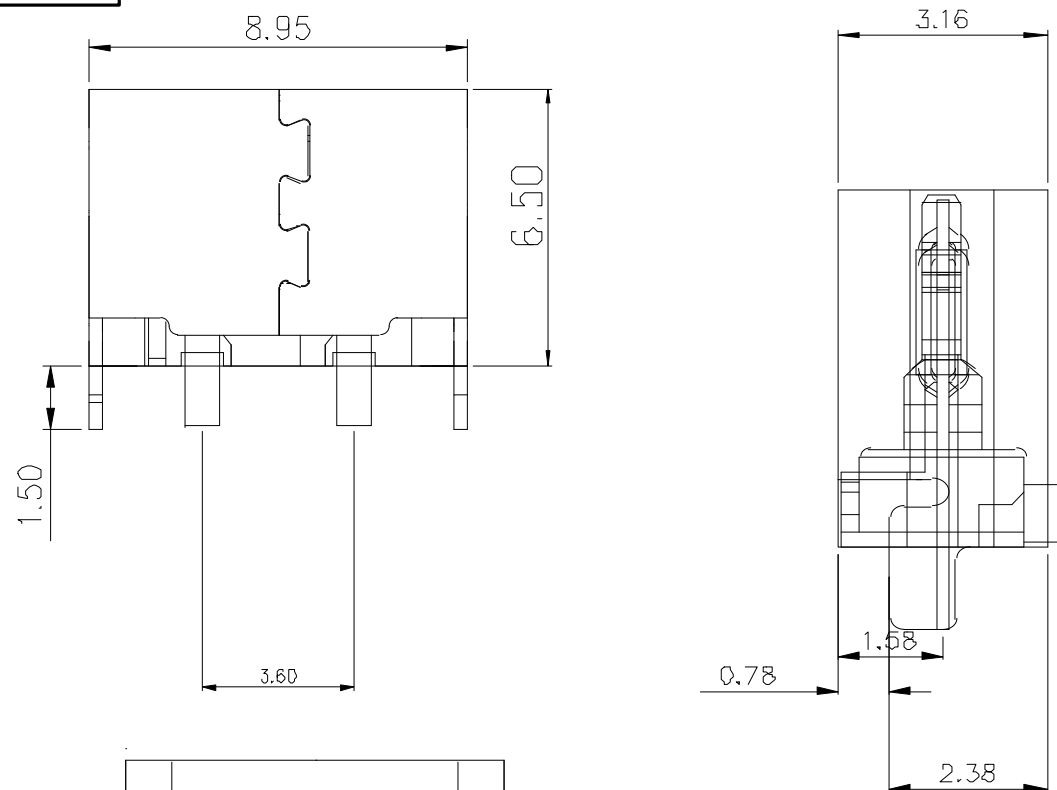


NOTE:

1.MATERIAL SPECIFICATION:

- 1.HOUSING: HIGH TEMPERATURE RESISTANT PLASTIC, UL94 V-0.
- 2.CONTACTS: COPPER ALLOY
- 3.MID PLATE: STAINLESS STEEL
- 4.FRONT SHELL: STAINLESS STEEL

2.PLATING SPECIFICATION:

2-1.CONTACTS:

Ni 50u" MIN. UNDER PLATED OVER ALL.

Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.

(GOLD PLATING THICKNESS FOLLOW THE P/N)

PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N

2-2.FRONT SHELL:

SEE TABLE 1.

2-3.SHIELD PLATE&EMI PLATE:

CLEAR ONLY

3.MECHANICAL PERFORMANCE,

3-1.INSERTION FORCE: 0.5~2.0kgf.

3-2.REMOVAL FORCE: 0.8kgf~2.0kgf.

3-3.DURABILITY: 5000 CYCLES.

4.ELECTRICAL PERFORMANCE,

4-1. CURRENT RATING: 3.0A

VOLTAGE RATING: 5.0V

4-2. LLCR:

VBUS & GND PINS AND OTHER PINS: 40mΩ/PIN MAX.

SHIELD: 50mΩ/MAX.

LLCR MAX. CHANGE OF ALL PINS: 10mΩ.

4-3.INSULATION RESISTANCE: 100MΩ MIN

4-4.DIELECTRIC WITHSTAND VOLTAGE, AC 100V FOR 1 MINUTE.

5. ENVIRONMENTAL PERFORMANCE:

OPERATING TEMPERATURE: -25°C~+85°C.

6.IR REFLOW:

THE PEAK TEMPERATURE ON THE BOARD SHALL
BE MAINTAINED FOR 10 SECONDS AT 260°C.

负极

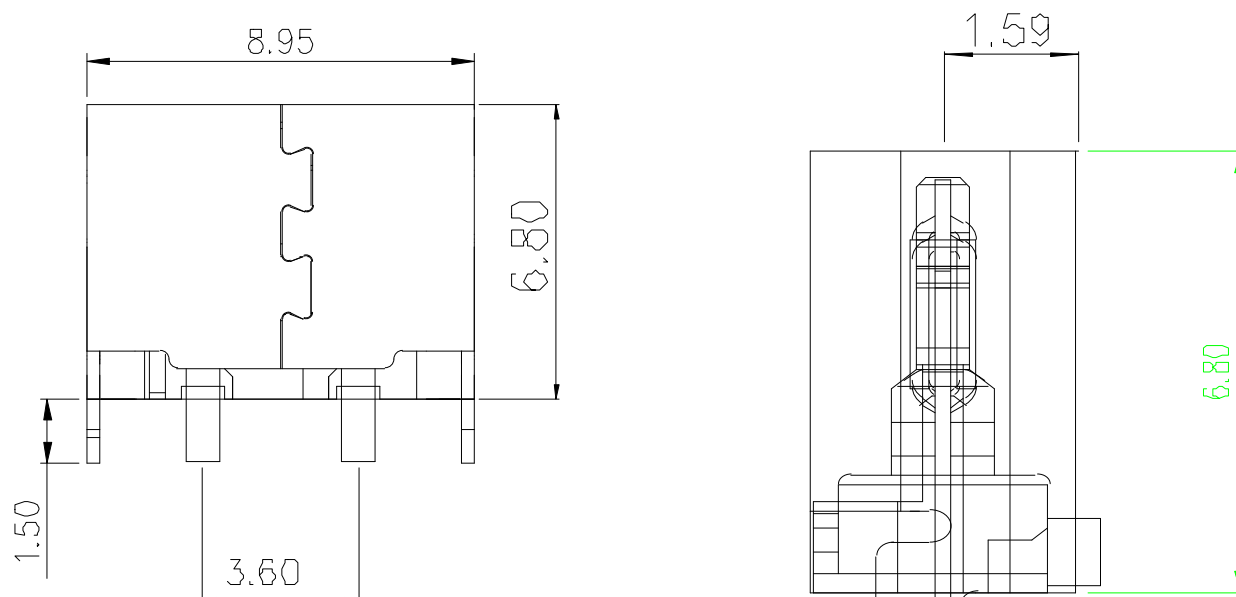
负极

正极

正极

东莞市溪榜电子有限公司
DONG GUAN XIBANG ELECTRONICS CO., LTD.

TOLERANCE: X.X ±0.30 X.XX ±0.20 X.XXX ±0.10 X.° ±10° .X° ±5° .X° ±5°	DRAWN BY :	DATE :	PART NAME:	
		2015.08.18	TYPE-C2PIN立插板H6.5	
	CHECKED BY :	DATE :	PART NO.	SEE TABLE
		2015.08.18	MOLD NO.	
UNIT: mm [inch] SCALE: 1:1 SIZE: A4	APPROVED BY :	DATE :	DRAW NO.	
		2015.08.18	SHEET NO.	1 OF 1



NOTE:

1.MATERIAL SPECIFICATION:

- 1.HOUSING: HIGH TEMPERATURE RESISTANT PLASTIC, UL94 V-0.
- 2.CONTACTS: COPPER ALLOY
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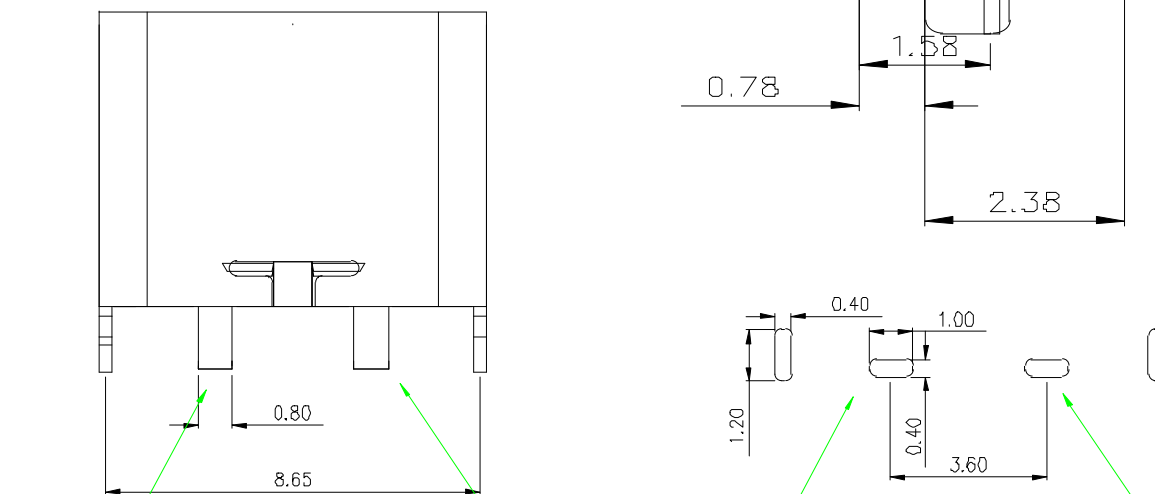
4-3.INSULATION RESISTANCE: 100MΩ MIN

4-4.DIELECTRIC WITHSTAND VOLTAGE, AC 100V FOR 1 MINUTE.

5. ENVIRONMENTAL PERFORMANCE:

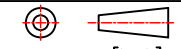
OPERATING TEMPERATURE: -25°C~+85°C.

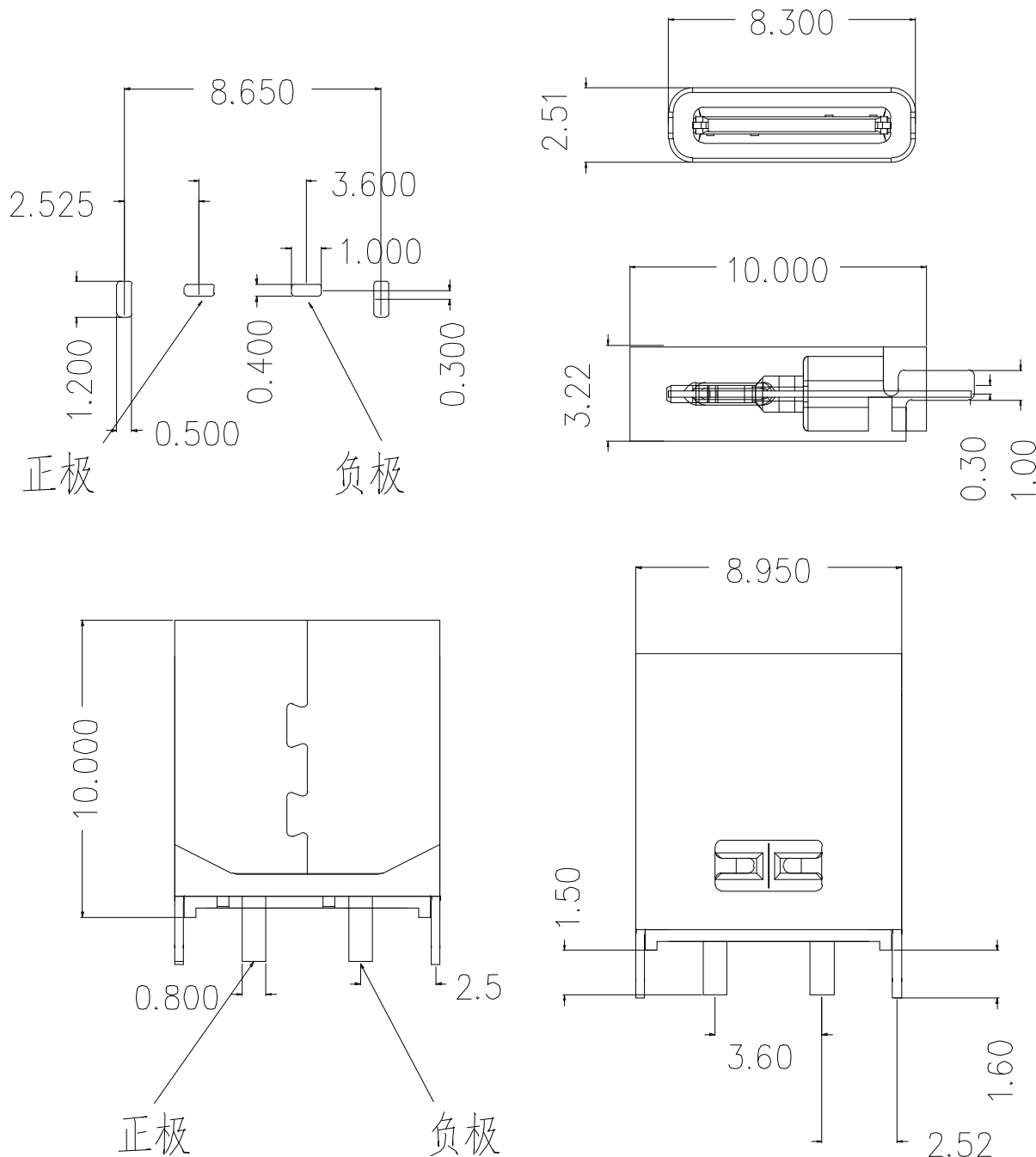
6.IR REFLOW:

THE PEAK TEMPERATURE ON THE BOARD SHALL
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东莞市溪榜电子有限公司

DONG GUAN XIBANG ELECTRONICS CO., LTD.

TOLERANCE: X.X ±0.30 X.XX ±0.20 X.XXX ±0.10 X.° ±10° X.° ±5° X.° ±5°	DRAWN BY :	DATE :	PART NAME:	
		2015.08.18	TYPE-C2PIN立插板H6.8	
	CHECKED BY :	DATE :	PART NO.	SEE TABLE
		2015.08.18	MOLD NO.	
 UNIT: mm [inch]	APPROVED BY :	DATE :	DRAW NO:	
		2015.08.18	SHEET NO.	1 OF 1
SCALE: 1:1	SIZE: A4			



NOTE:

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- 4.FRONT SHELL: STAINLESS STEEL

2.PLATING SPECIFICATION:

2-1.CONTACTS:

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Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.

(GOLD PLATING THICKNESS FOLLOW THE P/N)

PLATING SPECIFICATIONS OF THE SOLDER AREA FOLLOW THE P/N

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SEE TABLE 1.

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CLEAR ONLY

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5. ENVIRONMENTAL PERFORMANCE:

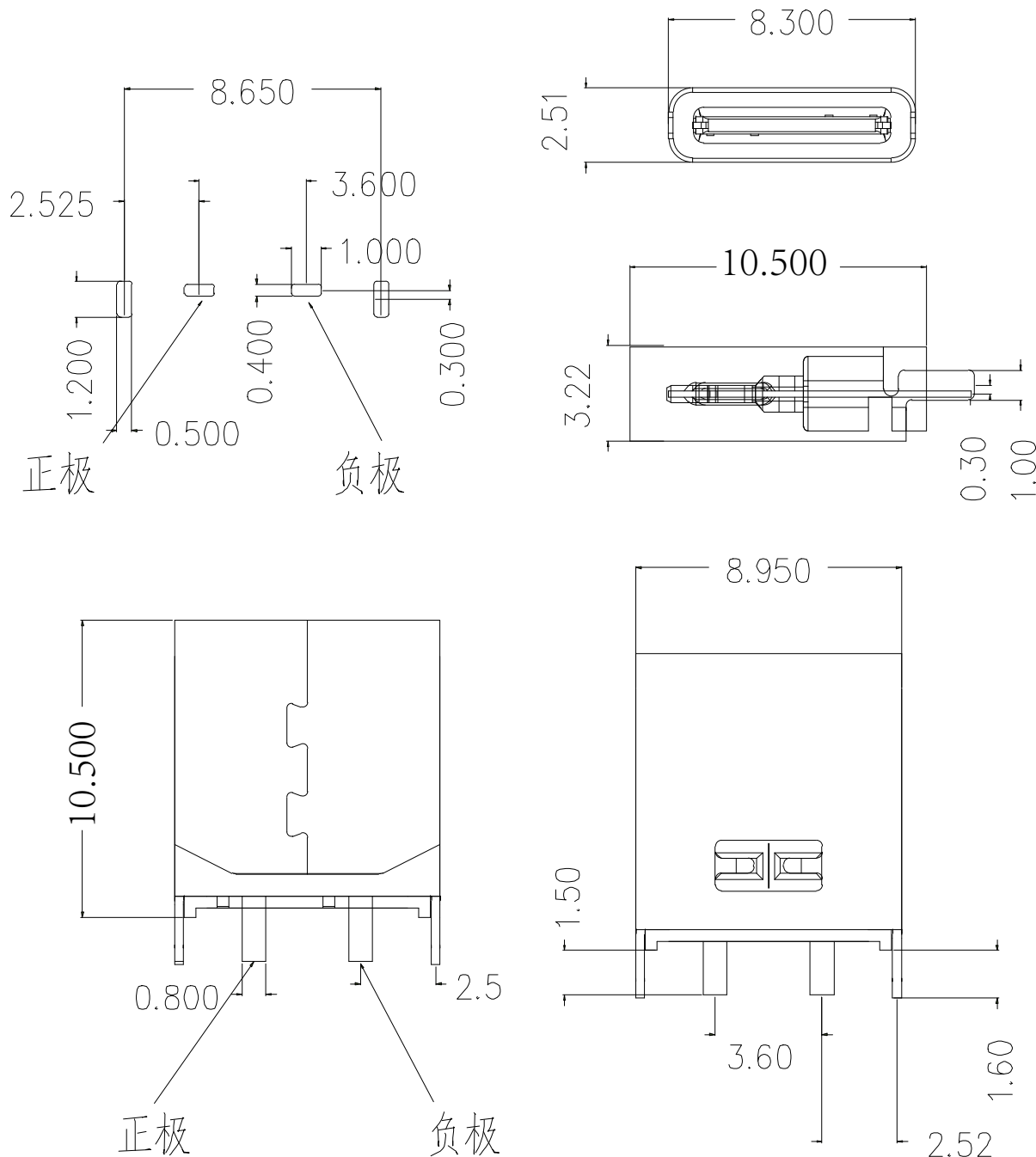
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DONG GUAN XIBANG ELECTRONICS CO., LTD.

TOLERANCE: X.X ±0.30 X.XX ±0.20 X.XXX ±0.10 X.° ±10° .X.° ±8° .X.° ±5° UNIT: mm [inch] SCALE:1:1 SIZE: A4	DRAWN BY :	DATE :	PART NAME:	
		2015.08.18	TYPE-C2PIN连接器H10.0	
	CHECKED BY:	DATE :	PART NO.	SEE TABLE
		2015.08.18	MOLD NO.	
	APPROVED BY:	DATE :	DRAW NO:	
		2015.08.18	SHEET NO.	1 OF 1



NOTE:

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		2015.08.18	TYPE-C2PIN立插板H10.5	
	CHECKED BY:	DATE :	PART NO.	SEE TABLE
		2015.08.18	MOLD NO.	
	APPROVED BY:	DATE :	DRAW NO:	
		2015.08.18	SHEET NO.	1 OF 1